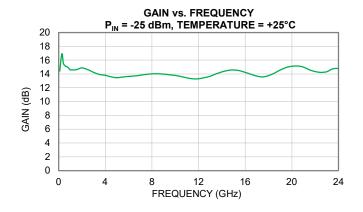
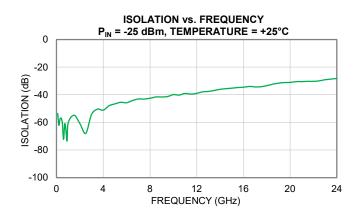
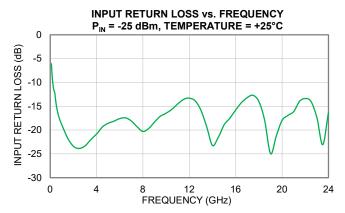
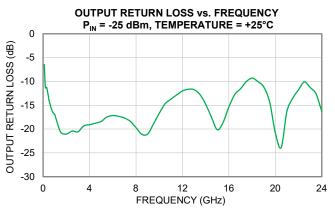
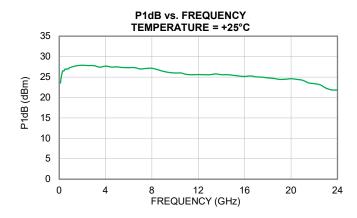
Note: Data was taken at V_{DD} = +10 V and V_{GG2} = +3.5 V. At +25°C, V_{GG1} has been adjusted to achieve I_{DD} = 300 mA. For over voltage and temperature data, see AVA-223MP+.

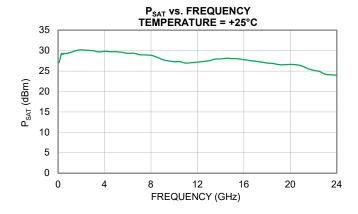




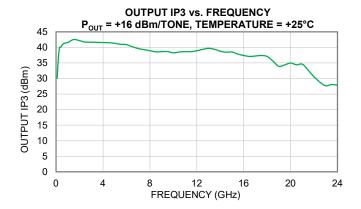


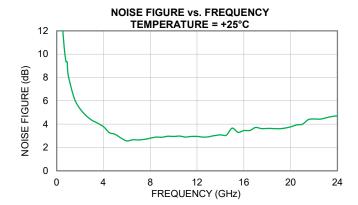




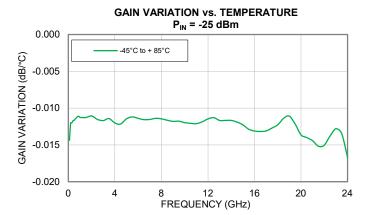


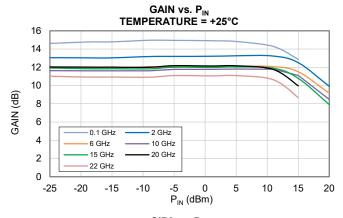
Note: Data was taken at V_{DD} = +10 V and V_{GG2} = +3.5 V. At +25°C, V_{GG1} has been adjusted to achieve I_{DD} = 300 mA. For over voltage and temperature data, see AVA-223MP+.

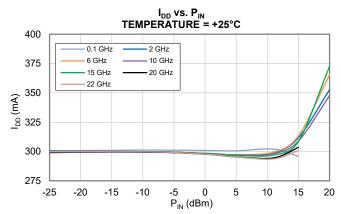


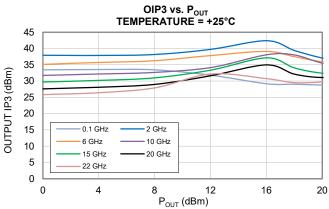


Note: All data taken in this section represents the Die attached in a 5x5mm 32-Lead QFN-style package and measured on Mini-Circuits Characterization Test Board TB-AVA-223MPC+. Data was taken at V_{DD} = +10 V and V_{GG2} = +3.5 V. At +25°C, V_{GG1} has been adjusted to achieve I_{DD} = 300 mA.









Note: All data taken in this section represents the die measured on modified Mini-Circuits Die Characterization Test Board using external bias tee (Figure 4). Data was taken at V_{DD} = +10 V and V_{GG2} = +3.5 V. At +25°C, V_{GG1} has been adjusted to achieve I_{DD} = 300 mA.

